Chip Monolithic Ceramic Capacitors

muRata

Medium-voltage High-Capacitance for General-Use

Features

- 1. A new monolithic structure for small, high capacitance capable of operating at high voltage levels.
- 2. Sn-plated external electrodes realized good solderability.
- 3. Use the GRM18/21/31 types with flow or reflow
- soldering, and other types with reflow soldering only.

Applications

- 1. Ideal for use as a hot-cold coupling for DC/DC converter.
- 2. Ideal for use on line filters and ringer detectors for telephones, facsimiles and modems.
- 3. Ideal for use on diode-snubber circuits for switching power supplies.

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Part Number			nensions (mm	1)		
	L	W	Т	е	g min.	
GRM188	1.6 ±0.1	0.8 ±0.1	0.8 ±0.1	0.2 to 0.5	0.4	
GRM21A GRM21B	2.0 ±0.2	1.25 ±0.2	1.0 +0,-0.3 1.25 ±0.2		0.7	
GRM31B	3.2 +0.2	1.6 +0.2	1.25 +0,-0.3			
GRM31C	J.Z <u>1</u> 0.Z	1.0 ±0.2	1.6 ±0.2		1.2	
GRM32Q	3.2 ±0.3 4.5 ±0.4	2.5 ±0.2 3.2 ±0.3	1.5 +0,-0.3	0.3 min.		
GRM32D			2.0 +0,-0.3			
GRM43Q GRM43D			1.5 +0,-0.3 2.0 +0,-0.3		2.2	
GRM55D	5.7 ±0.4	5.0 ±0.4	2.0 +0,-0.3		3.2*	
* GRM55DR73A : 2.5mm min.						

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM188R72E221KW07D	DC250	X7R (EIA)	220pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E331KW07D	DC250	X7R (EIA)	330pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E471KW07D	DC250	X7R (EIA)	470pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E681KW07D	DC250	X7R (EIA)	680pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM188R72E102KW07D	DC250	X7R (EIA)	1000pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E102KW01D	DC250	X7R (EIA)	1000pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E152KW07D	DC250	X7R (EIA)	1500pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E152KW01D	DC250	X7R (EIA)	1500pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM188R72E222KW07D	DC250	X7R (EIA)	2200pF ±10%	1.6	0.8	0.8	0.4	0.2 to 0.5
GRM21AR72E222KW01D	DC250	X7R (EIA)	2200pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E332KW01D	DC250	X7R (EIA)	3300pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E472KW01D	DC250	X7R (EIA)	4700pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21AR72E682KW01D	DC250	X7R (EIA)	6800pF ±10%	2.0	1.25	1.0	0.7	0.3 min.
GRM21BR72E103KW03L	DC250	X7R (EIA)	10000pF ±10%	2.0	1.25	1.25	0.7	0.3 min.
GRM31BR72E153KW01L	DC250	X7R (EIA)	15000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72E223KW01L	DC250	X7R (EIA)	22000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72E333KW03L	DC250	X7R (EIA)	33000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM31CR72E473KW03L	DC250	X7R (EIA)	47000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72E683KW01L	DC250	X7R (EIA)	68000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM31CR72E104KW03L	DC250	X7R (EIA)	0.10µF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32DR72E104KW01L	DC250	X7R (EIA)	0.10µF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72E154KW01L	DC250	X7R (EIA)	0.15µF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM32DR72E224KW01L	DC250	X7R (EIA)	0.22µF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR72E224KW01L	DC250	X7R (EIA)	0.22μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E334KW01L	DC250	X7R (EIA)	0.33μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM43DR72E474KW01L	DC250	X7R (EIA)	0.47µF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72E474KW01L	DC250	X7R (EIA)	0.47μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72E105KW01L	DC250	X7R (EIA)	1.0μF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR72J102KW01L	DC630	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J152KW01L	DC630	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J222KW01L	DC630	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.

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ANote Please read rating and ACAUTION (for storage, operating, rating, soldering, mounting and handling) in this PDF catalog to prevent smoking and/or burning, etc. This catalog has only typical specifications. Therefore, you are requested to approve our product specifications or to transact the approval sheet for product specifications before ordering.

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Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GRM31BR72J332KW01L	DC630	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J472KW01L	DC630	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J682KW01L	DC630	X7R (EIA)	6800pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR72J103KW01L	DC630	X7R (EIA)	10000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31CR72J153KW03L	DC630	X7R (EIA)	15000pF ±10%	3.2	1.6	1.6	1.2	0.3 min.
GRM32QR72J223KW01L	DC630	X7R (EIA)	22000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR72J333KW01L	DC630	X7R (EIA)	33000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR72J473KW01L	DC630	X7R (EIA)	47000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43QR72J683KW01L	DC630	X7R (EIA)	68000pF ±10%	4.5	3.2	1.5	2.2	0.3 min.
GRM43DR72J104KW01L	DC630	X7R (EIA)	0.10µF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR72J154KW01L	DC630	X7R (EIA)	0.15µF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM55DR72J224KW01L	DC630	X7R (EIA)	0.22µF ±10%	5.7	5.0	2.0	3.2	0.3 min.
GRM31BR73A102KW01L	DC1000	X7R (EIA)	1000pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A152KW01L	DC1000	X7R (EIA)	1500pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A222KW01L	DC1000	X7R (EIA)	2200pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A332KW01L	DC1000	X7R (EIA)	3300pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM31BR73A472KW01L	DC1000	X7R (EIA)	4700pF ±10%	3.2	1.6	1.25	1.2	0.3 min.
GRM32QR73A682KW01L	DC1000	X7R (EIA)	6800pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32QR73A103KW01L	DC1000	X7R (EIA)	10000pF ±10%	3.2	2.5	1.5	1.2	0.3 min.
GRM32DR73A153KW01L	DC1000	X7R (EIA)	15000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM32DR73A223KW01L	DC1000	X7R (EIA)	22000pF ±10%	3.2	2.5	2.0	1.2	0.3 min.
GRM43DR73A333KW01L	DC1000	X7R (EIA)	33000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM43DR73A473KW01L	DC1000	X7R (EIA)	47000pF ±10%	4.5	3.2	2.0	2.2	0.3 min.
GRM55DR73A104KW01L	DC1000	X7R (EIA)	0.10µF ±10%	5.7	5.0	2.0	2.5	0.3 min.



Specifications and Test Methods

No.	Ite	m	Specifications	Test Method			
1	Operating Temperatu	re Range	−55 to +125℃	-			
2	Appearan	се	No defects or abnormalities	Visual inspection			
3	Dimensior	าร	Within the specified dimensions	Using calipers			
4	Dielectric	Strength	No defects or abnormalities	No failure should be observed when 150% of the rated voltage (200% of the rated voltage in case of rated voltage : DC250V, 120% of the rated voltage in case of rated voltage : DC1kV) is applied between the terminations for 1 to 5 sec., provided the charge/discharge current is less than 50mA.			
5	Insulation R (I.R.)	esistance	C≧0.01μF : More than 100MΩ • μF C<0.01μF : More than 10,000MΩ	The insulation resistance should be measured with DC500 \pm 50V (DC250 \pm 50V in case of rated voltage : DC250V) and within 60 \pm 5 sec. of charging.			
6	Capacitan	ce	Within the specified tolerance	The capacitance/D.F. should be measured at 25°C at a frequency of 1±0.2kHz and a voltage of AC1±0.2V (r.m.s.) • Pretreatment			
7	Dissipatio Factor (D.		0.025 max.	Perform a heat treatment at 150^{+0}_{-10} °C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
8	Capacitance Temperature Characteristics Adhesive Strength of Termination		Cap. Change Within ±15% (Temp. Range : −55 to +125℃)	The range of capacitance change compared with the 25°C value within -55 to +125°C should be within the specified range. •Pretreatment Perform a heat treatment at 150 ⁺⁰ / ₋₁₀ °C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
9			No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.			
		A		Fig. 1			
10	Vibration Resistance D.F.		No defects or abnormalities Within the specified tolerance 0.025 max.	Solder the capacitor to the test jig (glass epoxy board). The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each 3 mutually perpendicular directions (total of 6 hrs.).			
				Glass Epoxy Board			
11	1 Deflection		No cracking or marking defects should occur. $\begin{array}{c ccccccccccccccccccccccccccccccccccc$	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. $\underbrace{200}_{\text{Capacitance meter}}^{50} \underbrace{\text{Pressurize}}_{\text{Flexure=1}}^{100} (\text{in mm})$ Fig. 3			

* "Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa



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Specifications and Test Methods

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No	o. Ite	tem Specifications		Test Method					
12	Solderab Terminat	•	75% of the terminations are to be soldered evenly and continuously.	Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in eutectic solder solution for 2±0.5 sec. at 235±5°c. Immersing speed : 25±2.5mm/s					
		Appearance	No marking defects	Preheat the c	Preheat the capacitor at 120 to 150° ° for 1 min. Immerse the capacitor in eutectic solder solution at $260\pm5^{\circ}$ ° for 10 ± 1 sec. Let sit at *room condition for 24 ± 2 hrs., then measure				
		Capacitance Change	Within ±10%	10±1 sec. Le					
		D.F.	0.025 max.	U	 Immersing speed : 25±2.5mm/s Pretreatment 				
	Resistance	D.I .			eat treatment at $150\pm_{18}^{\circ}$ ° for	60±5 min. and then			
13	to Soldering Heat	I.R.	C≥0.01μF : More than 100MΩ • μF C<0.01μF : More than 10,000MΩ	let sit for 24±2 hrs. at *room condition.					
				*Preheating f	*Preheating for more than 3.2×2.5mm				
	et4U.com	Dielectric	In accordance with item No.4	Step	Temperature	Time			
		Strength		1	100℃ to 120℃	<u>1 min.</u>			
				2	170°C to 200°C	1 min.			
		Appearance	No marking defects	Fix the capac	itor to the supporting jig (glass	epoxy board) showr			
		Capacitance Change	Within ±7.5%	 in Fig. 4 using a eutectic solder. Perform the 5 cycles according to the 4 heat treatments listed in the following table. 					
		D.F.	0.025 max.		able. =2 hrs. at *room condition, then	maasura			
						Time (min.)			
		I.R.	C≧0.01μF : More than 100MΩ • μF C<0.01μF : More than 10,000MΩ	Step 1	Temperature (℃) Min. Operating Temp.±3	30±3			
				2	Room Temp.	2 to 3			
				3	Max. Operating Temp.±2	30±3			
				4	Room Temp.	2 to 3			
	Cycle	Dielectric Strength	In accordance with item No.4	•Pretreatment Perform a heat treatment at 150 [±] ₁ % ^o C for 60±5 min. and ther let sit for 24±2 hrs. at *room condition.					
		Appearance	No marking defects						
		Capacitance Change	Within ±15%	for 500 ⁺²⁴ _o h	Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500 ^{±2} ° ₀ hrs. Remove and let sit for 24±2 hrs. at *room condition, then				
15	Humidity	D.F.	0.05 max.	measure.	let sit for 24 ± 2 hrs. at froom co	ondition, then			
10	6 (Steady State)	I.R.	C≥0.01μF : More than 10MΩ • μF C<0.01μF : More than 1,000MΩ	 Pretreatmer 	•Pretreatment Perform a heat treatment at 150^{+}_{-1} °C for 60±5 min. and then				
		Dielectric Strength	In accordance with item No.4		E2 hrs. at *room condition.				
		Appearance	No marking defects	Apply 120%	of the rated voltage (150% of th	e rated voltage in			
		Capacitance Change	Within ±15% (rated voltage : DC250V, DC630V) Within ±20% (rated voltage : DC1kV)	case of rated case of rated	Apply 120% of the rated voltage (150% of the rated voltage in case of rated voltage : DC250V, 110% of the rated voltage in case of rated voltage : DC1kV) for $1,000^{\pm48}$ hrs. at maximum operating temperature $\pm3^{\circ}$ C. Remove and let sit for 24 ±2 hrs. a				
		D.F.	0.05 max.	operating terr					
16	Life -	I.R.	C≧0.01μF : More than 10MΩ ∙ μF	The charge/d	 *room condition, then measure. The charge/discharge current is less than 50mA 				
		Dielectric	C<0.01μF : More than 1,000MΩ In accordance with item No.4	Apply test vo	 Pretreatment Apply test voltage for 60±5 min. at test temperature. Remove and let sit for 24±2 hrs. at *room condition. 				
		Strength Appearance	No marking defects						
		Appearance				1 10 7 4 4			
	Humidity Loading	Capacitance Change	Within ±15%	95% for 500	Apply the rated voltage at $40\pm2^{\circ}$ and relative humidity of 90 to 95% for $500\pm^{24}_{\circ}$ hrs.				
17	(Application ·	D.F.	0.05 max.	Remove and let sit for 24±2 hrs. at *room condition, then measure.					
17	DC250V, DC630V	I.R.	C≧0.01μF : More than 10MΩ • μF C<0.01μF : More than 1,000MΩ	 Pretreatment 	Pretreatment Apply test voltage for 60±5 min. at test temperature.				
	item)	Dielectric			Remove and let sit for 24 ± 2 hrs. at *room condition.				

* "Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa

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